



US00D719113S

(12) **United States Design Patent**
Sohn et al.

(10) **Patent No.:** **US D719,113 S**

(45) **Date of Patent:** **** Dec. 9, 2014**

(54) **SEMICONDUCTOR DEVICE**

(71) Applicant: **Samsung Electro-Mechanics Co., Ltd.**,
Suwon, Gyunggi-do (KR)

(72) Inventors: **Young Ho Sohn**, Gyunggi-do (KR); **Si Joong Yang**, Gyunggi-do (KR); **Young Ki Lee**, Gyunggi-do (KR); **Jin Su Kim**, Gyunggi-do (KR); **Dong Hwan Kim**, Gyunggi-do (KR); **Jong Man Kim**, Gyunggi-do (KR); **Kee Ju Um**, Gyunggi-do (KR); **Hyo Jin Lee**, Gyunggi-do (KR); **Young Hoon Kwak**, Gyunggi-do (KR)

(73) Assignee: **Samsung Electro-Mechanics Co., Ltd.**,
Suwon, Gyunggi-Do (KR)

(**) Term: **14 Years**

(21) Appl. No.: **29/450,491**

(22) Filed: **Mar. 18, 2013**

(30) **Foreign Application Priority Data**

Sep. 20, 2012 (KR) 30-2012-0045474

(51) **LOC (10) Cl.** **13-03**

(52) **U.S. Cl.**
USPC **D13/182**

(58) **Field of Classification Search**
USPC D13/110, 182, 184, 713, 728, 736, 760,
D13/761, 775, 679.01, 820, 361, 666, 668,
D13/678, 684, 690, 257, 71.5, 252, 324,
D13/250, 253, 174, 64, 65, 66, 438
See application file for complete search history.

(56) **References Cited**

U.S. PATENT DOCUMENTS

3,602,846 A * 8/1971 Hauser 333/140
3,762,039 A * 10/1973 Douglass et al. 29/827

3,825,876 A *	7/1974	Damon et al.	439/70
3,846,734 A *	11/1974	Pauza et al.	439/70
4,951,124 A *	8/1990	Sawaya	257/692
D357,462 S *	4/1995	Terasawa et al.	D13/182
D394,244 S *	5/1998	Majumdar et al.	D13/182
D396,846 S *	8/1998	Nakayama et al.	D13/182
D396,847 S *	8/1998	Nakayama et al.	D13/182
D401,912 S *	12/1998	Majumdar et al.	D13/182
D418,485 S *	1/2000	Kawafuji et al.	D13/182
D421,969 S *	3/2000	Kawafuji et al.	D13/182
D432,097 S *	10/2000	Song et al.	D13/182
D441,727 S *	5/2001	Sekimoto	D13/182
D448,739 S *	10/2001	Iwasaki et al.	
D459,705 S *	7/2002	Yokota et al.	D13/182
D466,485 S *	12/2002	Maehara et al.	D13/182
D470,463 S *	2/2003	Iwasaki et al.	D13/182
D470,824 S *	2/2003	Iwasaki et al.	D13/182
D470,825 S *	2/2003	Iwasaki et al.	D13/182
D472,530 S *	4/2003	Iwasaki et al.	D13/182
D505,399 S *	5/2005	Yoshida et al.	D13/182
D505,400 S *	5/2005	Kawafuji et al.	D13/182
D539,761 S *	4/2007	Takahashi et al.	D13/182
D548,202 S *	8/2007	Takahashi	D13/182

(Continued)

Primary Examiner — Elizabeth J Oswecki

(74) *Attorney, Agent, or Firm* — McDermott Will & Emery LLP

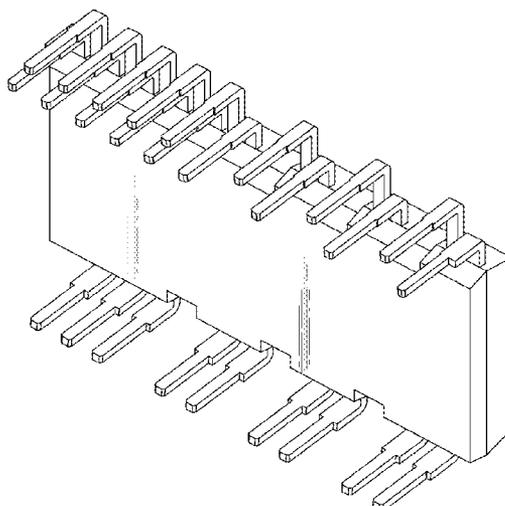
(57) **CLAIM**

The ornamental design for a semiconductor device, as shown and described.

DESCRIPTION

FIG. 1 is a perspective view of a semiconductor device showing our new design;
FIG. 2 is a front view thereof;
FIG. 3 is a rear view thereof;
FIG. 4 is a left side view thereof;
FIG. 5 is a right side view thereof;
FIG. 6 is a top plan view thereof; and,
FIG. 7 is a bottom plan view thereof.

1 Claim, 7 Drawing Sheets



(56)

References Cited

U.S. PATENT DOCUMENTS

D548,203 S *	8/2007	Takahashi	D13/182	D686,174 S *	7/2013	Soyano	D13/182
D653,633 S *	2/2012	Soyano	D13/182	D703,625 S *	4/2014	Lim et al.	D13/182
D653,634 S *	2/2012	Soyano	D13/182	D705,184 S *	5/2014	Takahashi et al.	D13/182
D674,760 S *	1/2013	Mochizuki et al.	D13/182	D706,232 S *	6/2014	Nakamura	D13/182
				2003/0042584 A1 *	3/2003	Yamaguchi	257/666
				2010/0149774 A1 *	6/2010	Matsumoto et al.	361/783

* cited by examiner

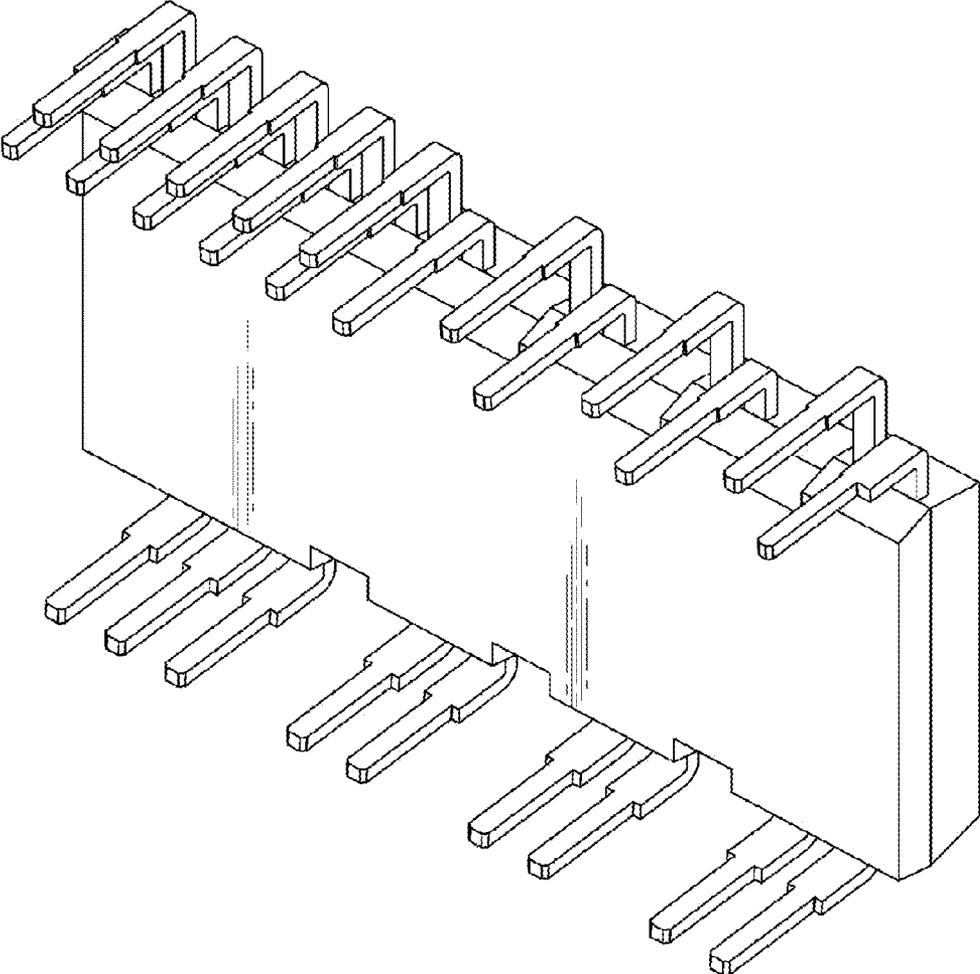


FIG. 1

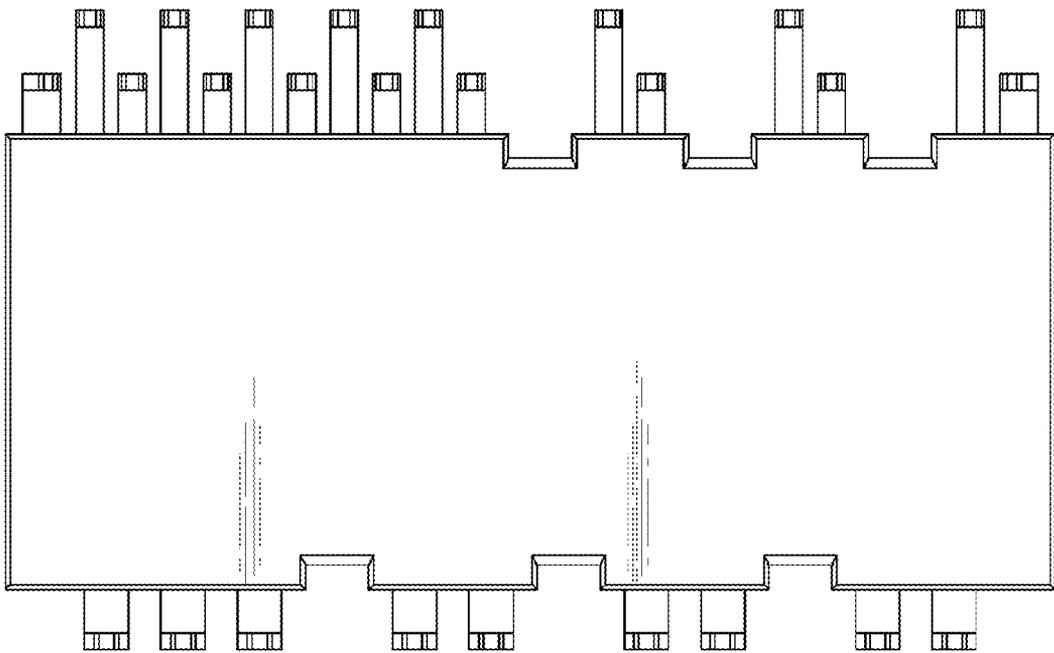


FIG. 2

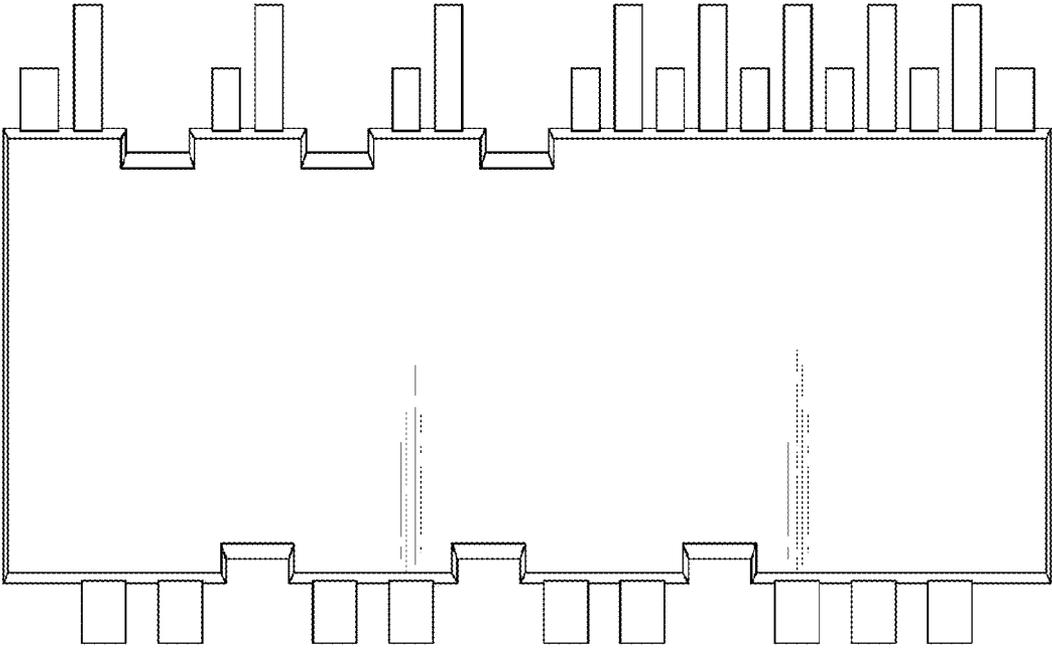


FIG. 3

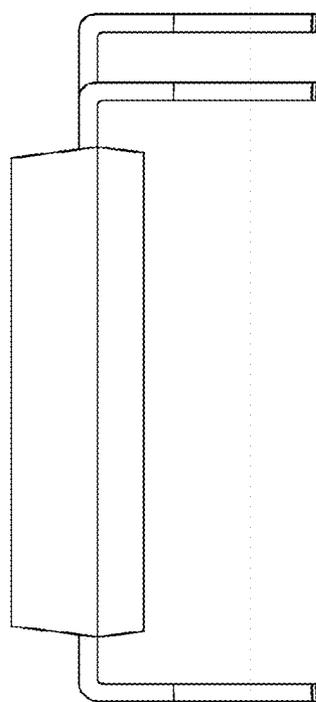


FIG. 4

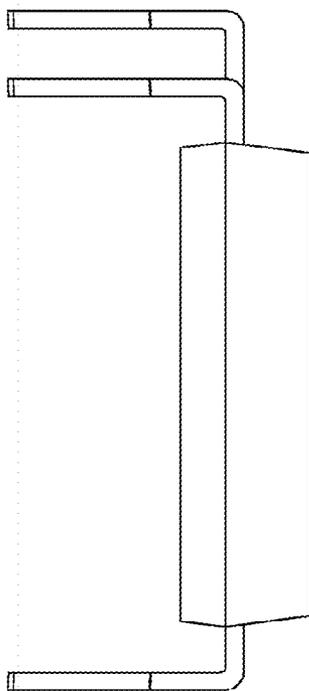


FIG. 5

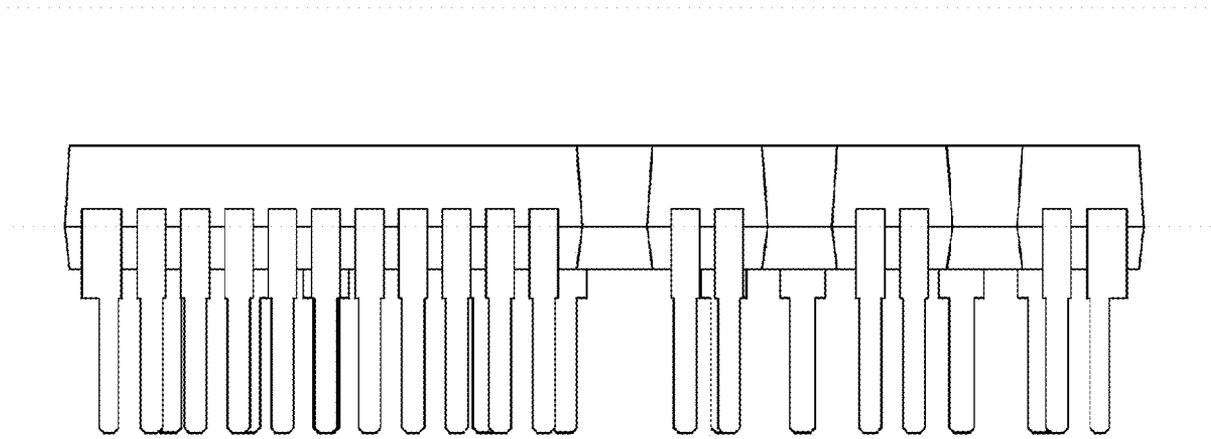


FIG. 6

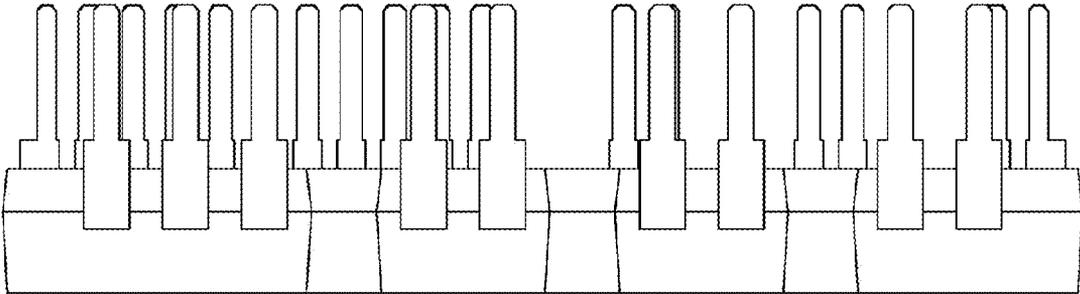


FIG. 7